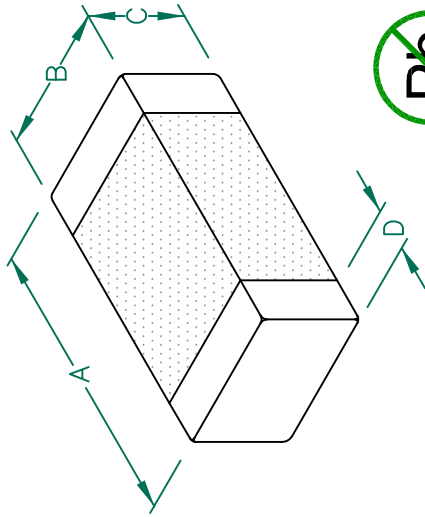


MI1206K601R-10

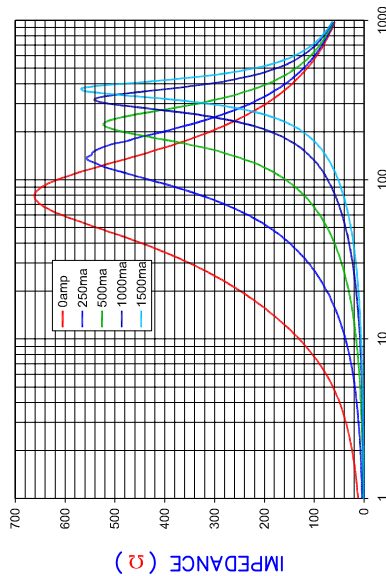
UNCONTROLLED
DOCUMENT

PHYSICAL DIMENSIONS:

A	3.20	[.126]	± 0.20	[.008]
B	1.60	[.063]	± 0.20	[.008]
C	1.10	[.043]	± 0.20	[.008]
D	0.51	[.020]	± 0.25	[.010]

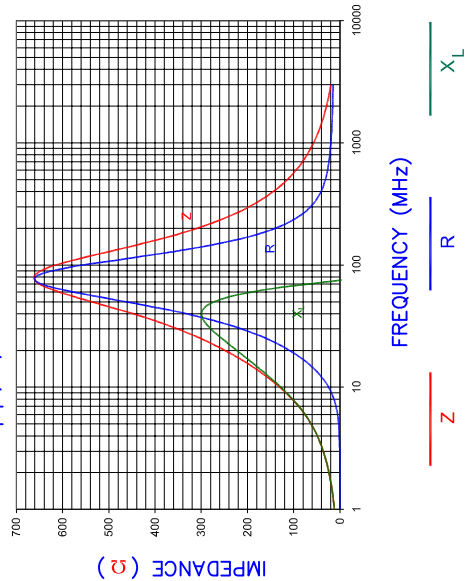


Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

|Z|, R, AND X vs. FREQUENCY

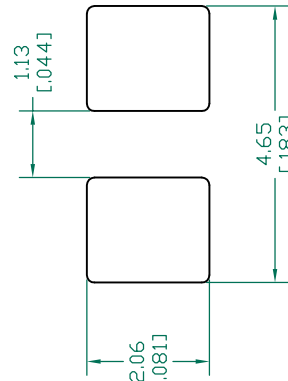


FREQUENCY (MHz)

NOTES: UNLESS OTHERWISE SPECIFIED

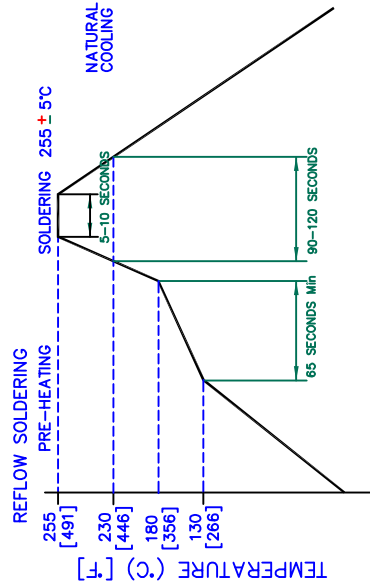
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762
(.030) to this dimension)

RECOMMENDED SOLDERING CONDITIONS



ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	600	
Minimum	450	
Maximum	750	1500 mA

RoHS
2002/95/EC

DIMENSIONS ARE IN mm [INCHES].

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Laird

REV	DATE	SCALE	NTS	SHEET
E	03/26/04	03/26/04	NTS	2 of 2
ADD OPERATING TEMPERATURE	08/05/13	Q1		
UPDATE LAIRD LOGO AND REFLOW CURVE	07/12/10	JUN		
CHANGE SOLDERING TEMPERATURE FROM 250	08/22/08	JRK		
UPDATE COMPANY LOGO	06/24/05	JRK		
ADD ROHS SYMBOL CHANGE CURRENT RATING	03/26/04	TMB		
A	ORIGINAL DRAFT			
REV	DESCRIPTION	DATE	INT	